



Drafts

Pending

Active

BRS:

L1: (1) ("6638411").PN.

L2: (54856) robot

L3: (233048) wafer

L4: (7242) 12 same 13

L5: (531) (205/123).CCLS.

L6: (16) 14 and 15

L7: (1) ("5989623").PN.

L8: (16686) (205/50-333).CCLS.

L9: (110) 14 and 18

L10: (94) 19 not 16

L11: (58) Backward citation search 1

Failed

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DB: US-Pat-Pub-USPAT-USOCH

Default generator: AOU

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Document ID	Issue Date	Pages	Title	Current OR	Current XRef	Inventor	U	S	C	P	1	PT
US 6328768 B1	20011211	12	Semiconductor device manufacturing line	29/25.01	118/719; 118/729	Ohta; Nahomi	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
US 6309520 B1	20011030	47	Methods and apparatus for processing the surface of a microelectronic workpiece	204/242	204/286.1; 204/288.3	Woodruff; Daniel J. et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
US 6294059 B1	20010925	26	Substrate plating apparatus	204/198	118/423; 118/429;	Hongo; Akihisa et al.	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
US 6203582 B1	20010320	72	Modular semiconductor workpiece processing tool	29/25.01	414/941	Berner; Robert W. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
US 6165050 A	20001226	20	Method of manufacturing semiconductor device using precision polishing	451/8	438/692; 438/693;	Ban; Mikichi et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
US 6132289 A	20001017	9	Apparatus and method for film thickness measurement integrated into a wafer	451/6	451/288; 451/66	Labunsky; Michael et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
US 6093291 A	20000725	11	Electroplating apparatus	204/224R	204/278.5; 204/284	Izumi; Takayuki et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
US 6071388 A	20000606	26	Electroplating workpiece fixture having liquid gap spacer	204/287	204/224R; 204/285;	Uzoh; Cyprian B.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
US 5723028 A	19980303	15	Electrodeposition apparatus with virtual anode	204/230.7	204/297.05; 257/E21.175;	Poris; Jaime	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
US 5718813 A	19980217	11	Enhanced reactive DC sputtering system	204/192.12	204/192.13; 204/192.15;	Drummond; Geoffrey N. et al.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
US 5705223 A	19980106	9	Method and apparatus for coating a semiconductor wafer	427/240	118/52; 427/348;	Bunkofsky; Raymond James	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>
US 5651865 A	19970729	12	Preferential sputtering of insulators from conductive targets	204/192.13	204/192.12; 204/192.22;	Selleys; Jeff C.	<input checked="" type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>	<input type="checkbox"/>

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Hts

Details

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